LNJ167W8RRA

Hight Bright Surface Mounting Chip LED

ESS Type

■ Absolute Maximum Ratings $T_a = 25$ °C

• Green

Parameter	Symbol	Rating	Unit	
Power dissipation	P_{D}	55	mW	
Forward current	I_{F}	20	mA	
Pulse forward current *	I_{FP}	60	mA	
Reverse voltage	V _R	4	V	
Operating ambient temperature	T _{opr}	-30 to +85	°C	
Storage temperature	T _{stg}	-40 to +100	°C	

Note) *: The condition of I_{FP} is duty 10%, Pulse width 1 msec.

• Red

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Note) *: The condition of I_{FP} is duty 10%, Pulse width 1 msec.

■ Electro-Optical Characteristics $T_a = 25$ °C±3°C

• Green

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Luminous intensity *1	I _O	$I_F = 5 \text{ mA}$	4.0	7.5	37.0	mcd
Forward current	I_R	$V_R = 4 V$			100	μΑ
Forward voltage	V_{F}	$I_F = 5 \text{ mA}$		1.95	2.30	V
Peak emission wavelength	$\lambda_{ m P}$	$I_F = 5 \text{ mA}$		575		nm
Dominant emission wavelength *2	λ_{d}	$I_F = 5 \text{ mA}$	561	572	576	nm
Spectral half band width	Δλ	$I_F = 5 \text{ mA}$		15		nm

Note) *1: Measurement tolerance: ±20% *2: Measurement tolerance: ±3 nm

■ Lighting Color

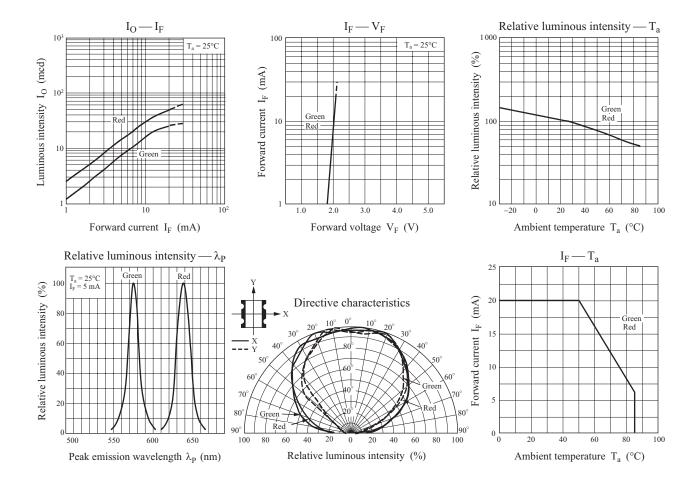
- Green
- Red

■ Electro-Optical Characteristics (Continued) $T_a = 25$ °C±3°C

• Red

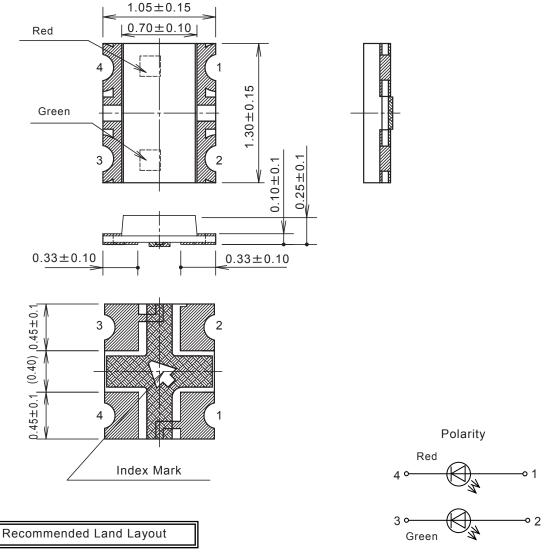
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Luminous intensity *1	I _O	$I_F = 5 \text{ mA}$	11.0	15.0	52.0	mcd
Reverse current	I_R	$V_R = 4 V$			100	μΑ
Forward voltage	V_{F}	$I_F = 5 \text{ mA}$		1.95	2.30	V
Peak emission wavelength	$\lambda_{ m P}$	$I_F = 5 \text{ mA}$		638		nm
Dominant emission wavelength *2	λ_{d}	$I_F = 5 \text{ mA}$	615	628	634	nm
Spectral half band width	Δλ	$I_F = 5 \text{ mA}$		20		nm

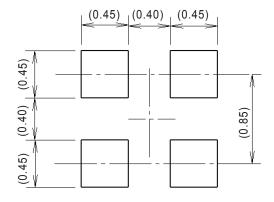
Note) *1: Measurement tolerance: ±20% *2: Measurement tolerance: ±3 nm



Ver. CEK 2

■ Package (Unit: mm)





- 1. Anode (Red)
- 2. Anode (Green)
- 3. Cathode (Green)
- 4. Cathode (Red)

(Note1)Electrode projection is not included in the package dimensions. (Note2)About solder thickness, please examine the products yourself completely. (Recommended thickness: t=0.10 mm~0.15 mm) (Note3)Do not install the pattern of the printed wiring board under LED.

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